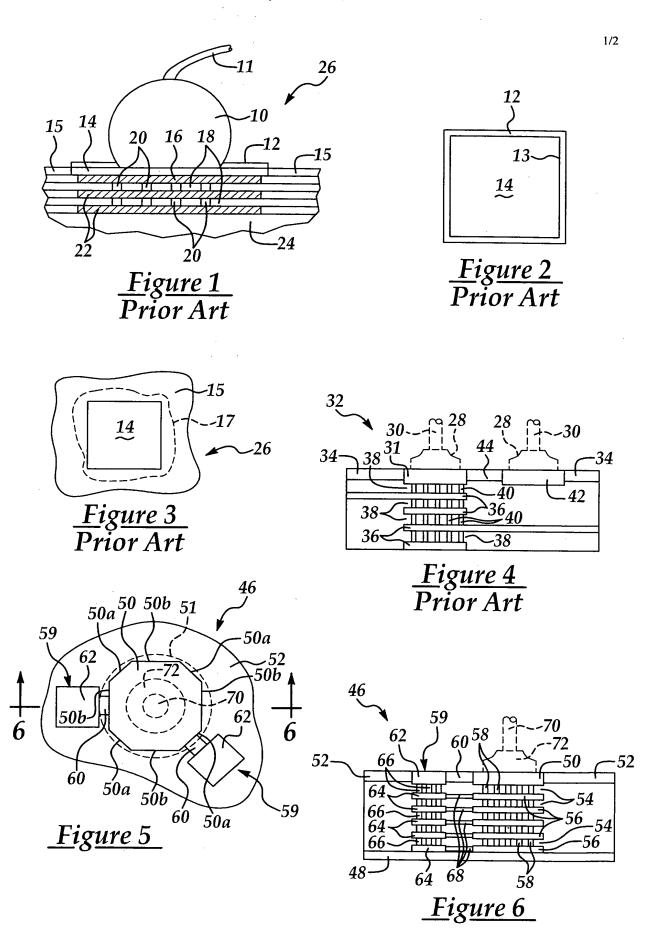
Inventor: Tai-Chun Huang Serial No.: To Be Assigned Filed: Herewith

For: Structure and Method For Reinforcing A Bond Pad On A Chip

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